## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Yew

Docket No: TI-26239.1

Serial No:

10/612,129

Examiner:

Cao, Phat X.

Filed:

7/2/2003

Art Unit:

2814

For:

DIRECT ATTACHMENT OF SEMICONDUCTOR CHIP TO ORGANIC

SUBSTRATE

## APPEAL BRIEF PURSUANT TO 1.192(c)

**Assistant Commissioner for Patents** Washington, DC 20231

Dear Sir:

CERTIFICATION OF FACSIMILE TRANSMISSION I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-

The following Appeal Brief is respectfully submitted in connection with the above identified application in response to the final rejection mailed August 6, 2004, and the Advisory Action mailed October 29, 2004.

## **REAL PARTY IN INTEREST**

The real party in interest is Texas Instruments Incorporated.

02/10/2005 GSTANLEY 00000600 and Act 108:2129

## RELATED APPEALS AND INTERFERENCES

Appellants legal representative knows of no appeals or interferences which will be directly affected, or have a bearing on the Board's decision.

TI-26239.1 Page 1 of 10